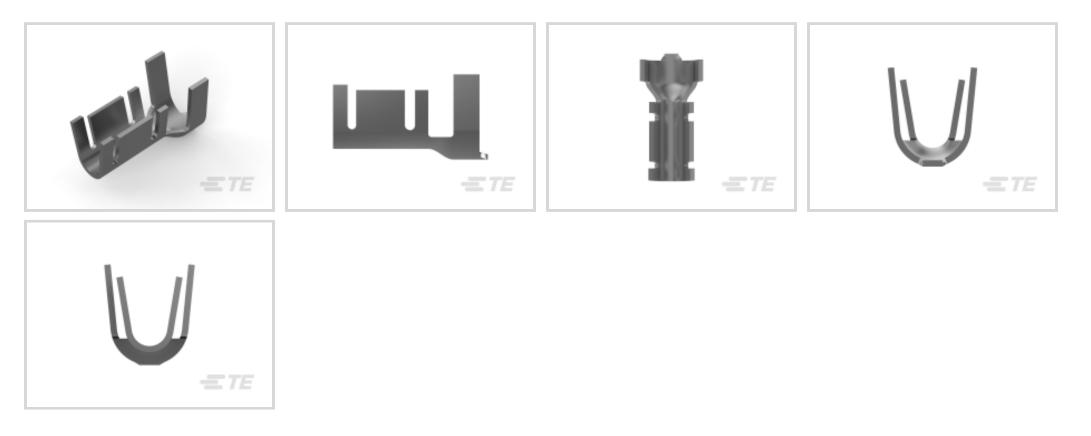


AMP-IN

TE Internal #: 3-647334-1 PCB Pin, 3.18 mm [.125 in] PCB Hole, 18 – 14 AWG, .8 – 2 mm² Wire, Through Hole - Solder, Tin Plating, Box, PCB Terminals View on TE.com >



Terminals & Splices > PCB Terminals



PCB Terminal Type: PCB Pin

PCB Thickness (Recommended): 1.57 mm [.062 in]

PCB Hole Diameter: 3.18 mm [.125 in]

Profile Height from PCB: 4.7 mm [.187 in]

Compatible Insulation Diameter (Max): 3.81 mm [.15 in]

Features

Product Type Features

Terminal Features	Stud Hole
Contact Features	
Terminal Plating Finish	Bright
Contact Mating Area Plating Material Thickness	5.08 μm[200 μin]
PCB Terminal Type	PCB Pin
Terminal Plating Material	Tin
Terminal Size	Miniature
Terminal Orientation	Straight
Termination Features	
Termination Method to PCB	Through Hole - Solder
Product Terminates To	Printed Circuit Board
Mechanical Attachment	
Wire Insulation Support	With
Dimensions	

3-647334-1

PCB Pin, 3.18 mm [.125 in] PCB Hole, 18 – 14 AWG, .8 – 2 mm² Wire, Through Hole - Solder, Tin Plating, Box, PCB Terminals



Extension Below Board	3.18 mm[.125 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
PCB Hole Diameter	3.18 mm[.125 in]
Profile Height from PCB	4.7 mm[.187 in]
Compatible Insulation Diameter (Max)	3.81 mm[.15 in]
Compatible Insulation Diameter Range	2.29 – 3.81 mm[.09 – .15 in]
Wire Size	.8 – 2 mm ²
Usage Conditions	
Insulation Option	Uninsulated
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Packaging Features	
Packaging Quantity	3000
Packaging Method	Box
Product Compliance For compliance documentation, visit the product page on TE.com>	

ELLELV Directive 2000/53/EC

EU RoHS Directive 2011/65/EU

Compliant

Compliant

EU ELV DIrective 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

3-647334-1

PCB Pin, 3.18 mm [.125 in] PCB Hole, 18 – 14 AWG, .8 – 2 mm² Wire, Through Hole - Solder, Tin Plating, Box, PCB Terminals



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought



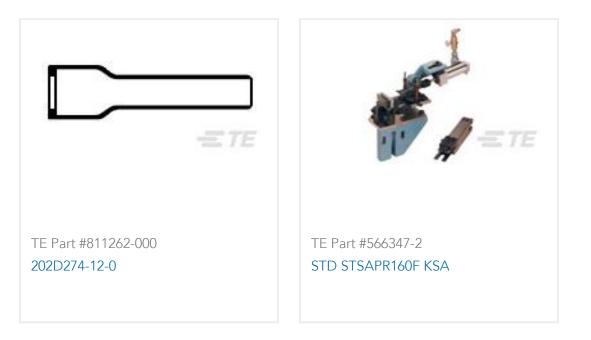












Documents

Product Drawings MINI AMP-IN 2000,14-18 AWG LF

English

3-647334-1

PCB Pin, 3.18 mm [.125 in] PCB Hole, 18 – 14 AWG, .8 – 2 mm² Wire, Through Hole - Solder, Tin Plating, Box, PCB Terminals



CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_3-647334-1_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_3-647334-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_3-647334-1_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product SpecificationsApplication SpecificationEnglishApplication SpecificationEnglish